

## Electrostatic Discharged Protection Devices (ESD) Data Sheet

### Description

The UBD32C05L01 of transient voltage suppressors are designed to protect low voltage, state-of-the-art CMOS semiconductors from transients caused by electrostatic discharge (ESD), cable discharge events (CDE), lightning and other induced voltage surges. The device is constructed using EPD process technology. The EPD process provides low standoff voltages with significant reductions in leakage currents and capacitance over silicon avalanche diode processes. This combined with low leakage current, means signal integrity is preserved in high-speed applications such as 10/100/1000 Ethernet. The device may be used to protect two high-speed line pairs. The "flow-thru" design minimizes trace inductance and reduces voltage overshoot associated with ESD events. The low clamping voltage of the device minimizes the stress on the protected IC. The device TVS diodes will meet the surge requirements of IEC61000-4-2, Level 4.

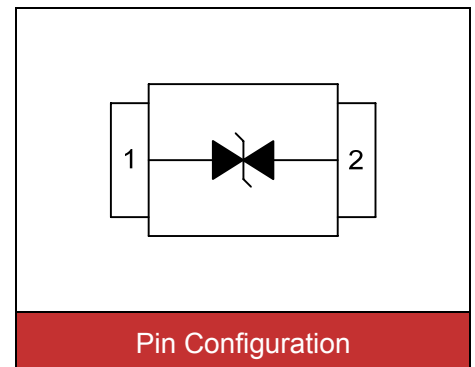


Contact : ±8kV  
Air : ±15kV



### Features

- IEC61000-4-2 ESD 15KV Air, 8KV contact compliance
- SOD-323 surface mount package
- Protects one I/O line
- Working voltage: 5V
- Low leakage current
- Low operating and clamping voltages
- Solid-state silicon avalanche technology
- Lead Free/RoHS compliant
- Solder reflow temperature: Pure Tin-Sn, 260~270°C
- Flammability rating UL 94V-0
- Meets MSL level 1, per J-STD-020
- Marking: 35



### Applications

- High-speed data lines
- Notebook, Laptop and Palmtop computers
- Microprocessor based equipment
- Portable instrumentation
- LAN / WAN equipment
- Peripherals
- Desktops PC and servers
- Universal serial bus (USB) port protection

### Maximum Ratings

Rating	Symbol	Value	Unit
Peak pulse current (tp=8/20μs waveform)	I <sub>PP</sub>	3	A
ESD voltage (Contact discharge)	V <sub>ESD</sub>	±8	kV
ESD voltage (Air discharge)		±15	
Lead soldering temperature	T <sub>L</sub>	260	°C
Storage & operating temperature range	T <sub>STG</sub> , T <sub>J</sub>	-55~+150	°C

Electrical Characteristics ( $T_J=25^{\circ}\text{C}$ )

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Reverse stand-off voltage	$V_{RWM}$				5	V
Reverse breakdown voltage	$V_{BR}$	$I_{BR}=1\text{mA}$	6			V
Reverse leakage current	$I_R$	$V_R=5\text{V}$			1	$\mu\text{A}$
Clamping voltage ( $t_p=8/20\mu\text{s}$ )	$V_C$	$I_{PP}=1\text{A}$			11	V
Clamping voltage ( $t_p=8/20\mu\text{s}$ )	$V_C$	$I_{PP}=3\text{A}$			20	V
Off state junction capacitance	$C_J$	0Vdc, f=1MHz		0.4		pF

Typical Characteristics Curves

Figure 1. Power Derating Curve

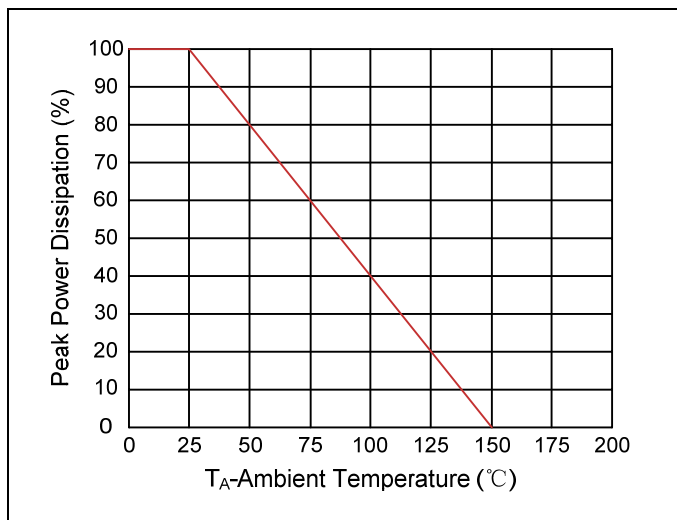


Figure 2. Pulse Waveform

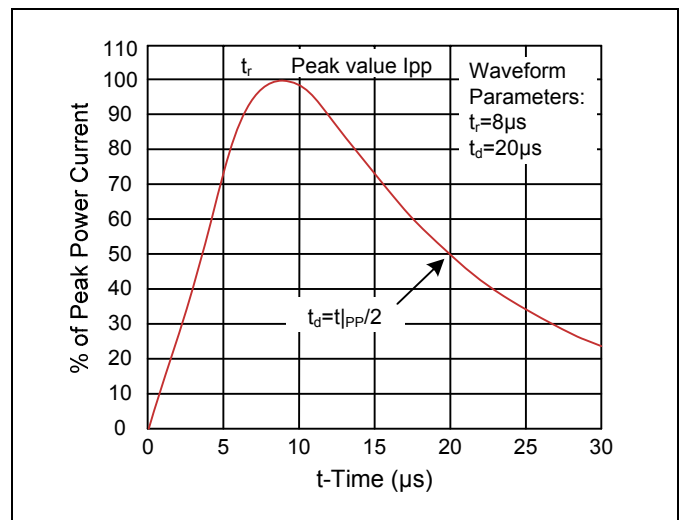


Figure 3. Normalized Capacitance vs. Reverse Voltage

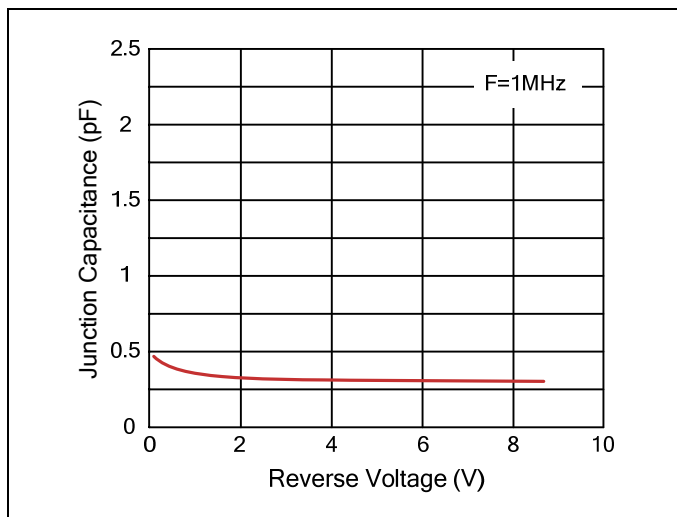
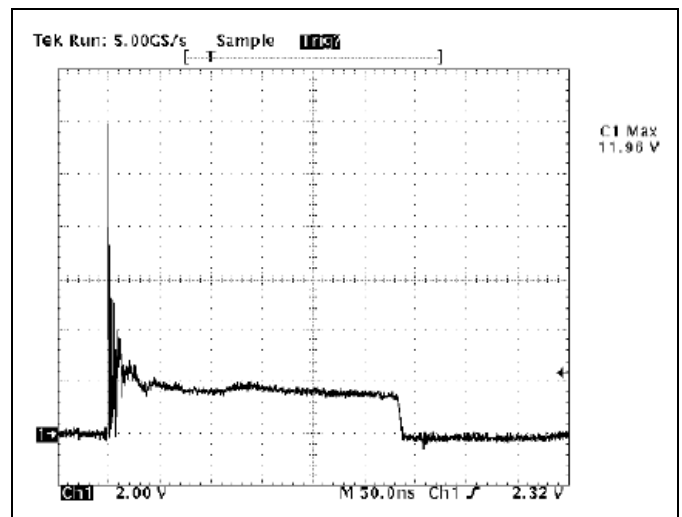
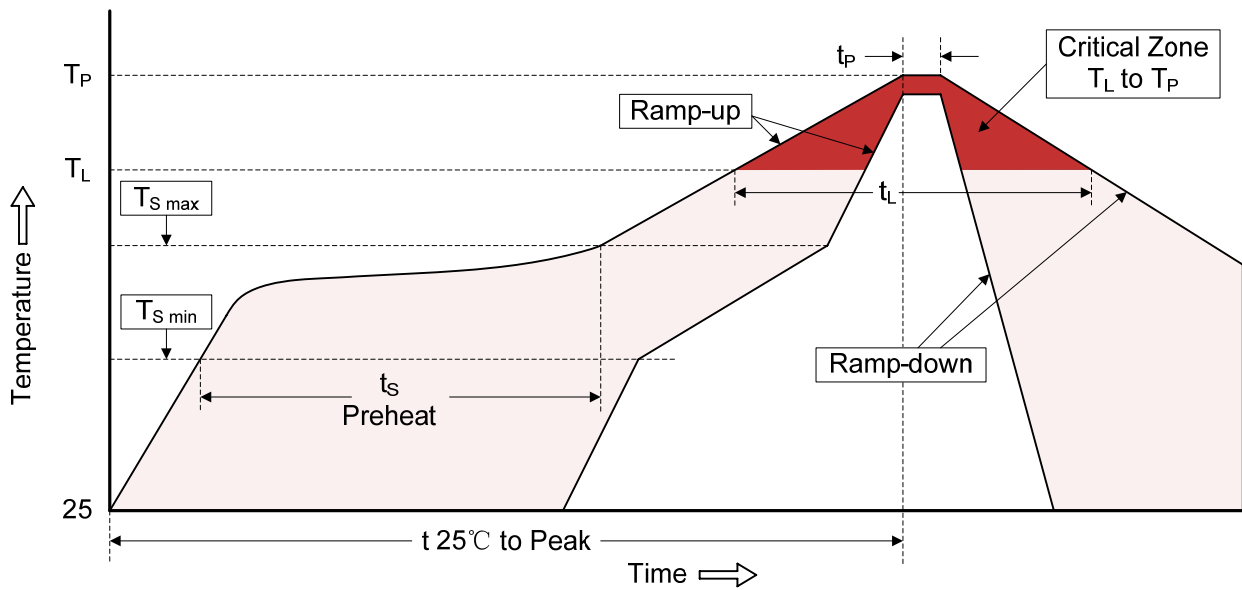


Figure 4. ESD Clamping (8kV Contact IEC61000-4-2)



Recommended Soldering Conditions

Reflow Soldering



Recommended Condition

Profile Feature	Pb-Free Assembly
Average ramp-up rate ( $T_L$ to $T_P$ )	3°C/second max.
Preheat -Temperature Min ( $T_{S\ min}$ ) -Temperature Max ( $T_{S\ max}$ ) -Time (min to max) ( $t_s$ )	150°C 200°C 60-180 seconds
$T_{S\ max}$ to $T_L$ -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature ( $T_L$ ) -Time ( $t_L$ )	217°C 60-150 seconds
Peak Temperature ( $T_P$ )	260°C
Time within 5°C of actual Peak Temperature ( $t_P$ )	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Dimensions (SOD-323)

	Dimension			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
	A	0.80	1.10	0.031
B	-	0.10	-	0.004
C	0.20	-	0.008	-
D	0.10	0.25	0.004	0.010
E	1.15	1.35	0.045	0.053
F	0.25	0.40	0.010	0.016
G	1.60	1.80	0.063	0.071
H	2.30	2.70	0.091	0.106

Packaging

<p>Tape</p>	Symbol	Dimension (mm)
	W	8.00±0.30
	P0	4.00±0.10
	P1	4.00±0.10
	P2	2.00±0.10
	D0	Φ1.55±0.10
	D1	Φ1.00±0.05
	E	1.75±0.10
	F	3.50±0.10
	A	1.48±0.10
	A0	0.80±0.10
	B	3.00±0.10
	B0	1.80±0.10
	K	1.05±0.10
t	0.25±0.05	
<p>Reel</p>	D	Φ178.0±2.0
	D2	Φ13.0
	W1	9.5
	Quantity: 3000PCS	

单击下面可查看定价，库存，交付和生命周期等信息

[>>Brightking\(君耀电子\)](#)